

# TEMIC

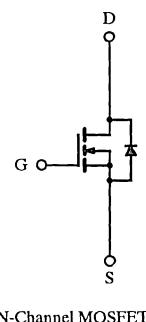
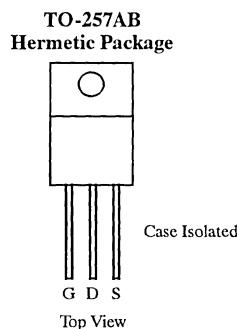
Siliconix

# 2N7085

## N-Channel Enhancement-Mode Transistor

### Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
100	0.075	20



### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage		$\pm 20$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )	$I_D$	20	A
		12	
Pulsed Drain Current	$I_{DM}$	80	
Maximum Power Dissipation	$P_D$	60	W
		20	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$
Lead Temperature ( $1/16''$ from case for 10 sec.)	$T_L$	300	

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N-P-Channel  
MOSFETs

### Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	$R_{thJA}$	80	2.1	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{thJC}$			
Case-to-Sink	$R_{thCS}$	1.0		

Specifications ( $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ <sup>a</sup>	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			25	$\mu\text{A}$
		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	
On-State Drain Current <sup>b</sup>	$I_{D(\text{on})}$	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}$	20			A
Drain-Source On-State Resistance <sup>b</sup>	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		0.06	0.075	$\Omega$
		$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}, T_J = 125^\circ\text{C}$		0.11	0.14	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}, I_D = 12 \text{ A}$	5.0	8.0		S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1400		pF
Output Capacitance	$C_{oss}$			480		
Reverse Transfer Capacitance	$C_{rss}$			110		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		35	50	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			10	20	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			18	25	
Turn-On Delay Time <sup>c</sup>	$t_{d(\text{on})}$	$V_{DD} = 50 \text{ V}, R_L = 2.5 \Omega$ $I_D \approx 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 4.7 \Omega$		13	30	ns
Rise Time <sup>c</sup>	$t_r$			85	120	
Turn-Off Delay Time <sup>c</sup>	$t_{d(\text{off})}$			35	80	
Fall Time <sup>c</sup>	$t_f$			75	95	
<b>Source-Drain Diode Ratings and Characteristics</b>						
Continuous Current	$I_S$				20	A
Pulsed Current	$I_{SM}$				80	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$			2.5	V
Reverse Recovery Time	$t_{rr}$	$I_F = 20 \text{ A}, \text{di}/dt = 100 \text{ A}/\mu\text{s}$		150	400	ns
Reverse Recovery Charge	$Q_{rr}$			0.5		$\mu\text{C}$

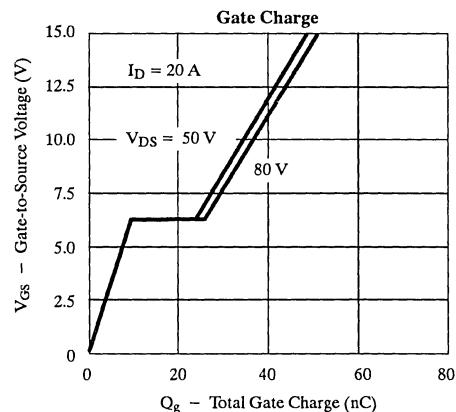
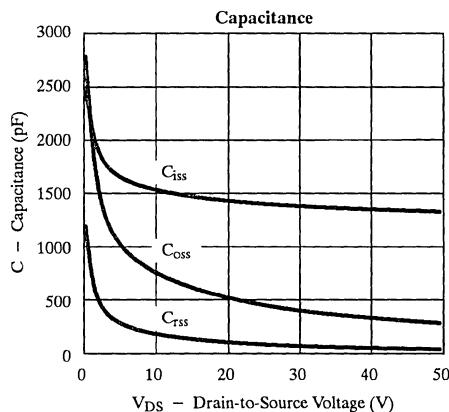
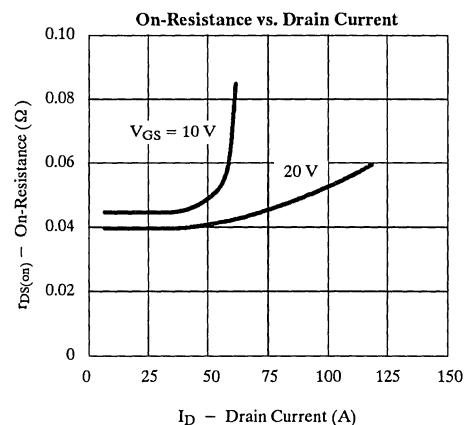
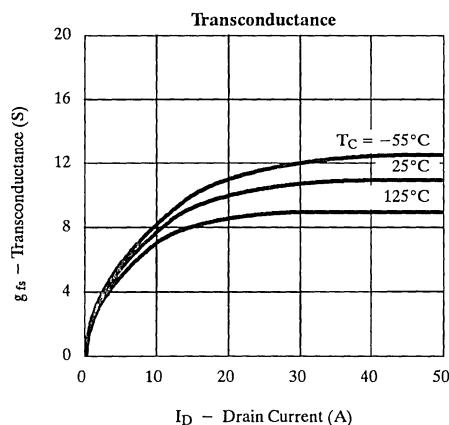
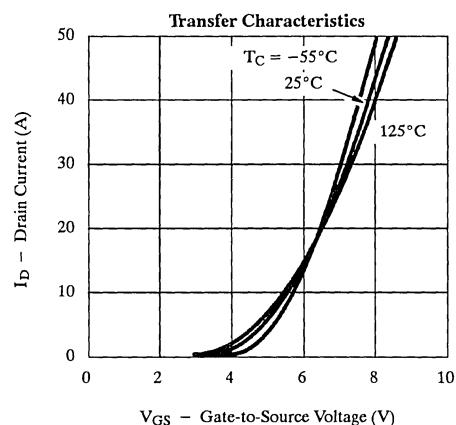
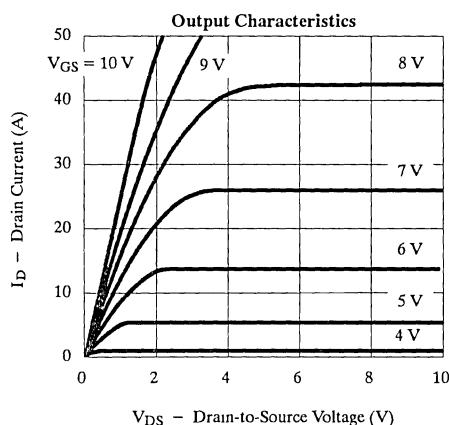
Notes:

a. For design aid only; not subject to production testing.

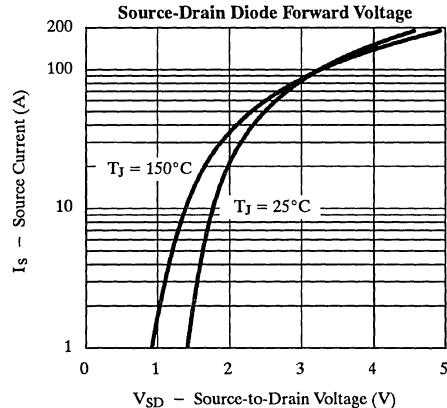
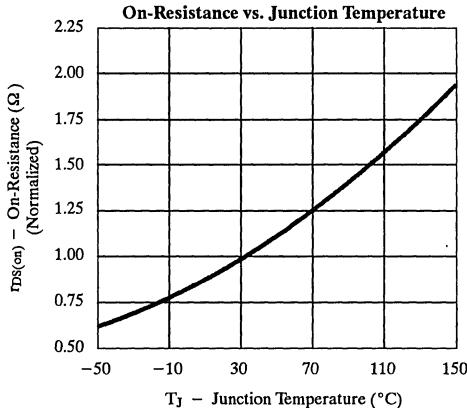
b. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

c. Independent of operating temperature.

## Typical Characteristics (25°C Unless Otherwise Noted)



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## Thermal Ratings

